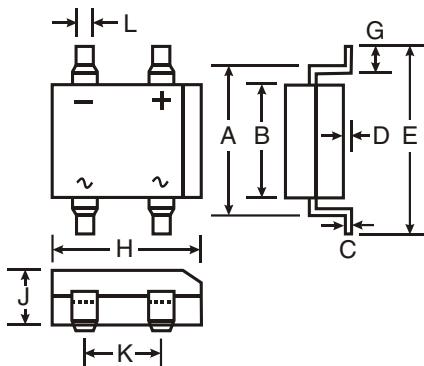


Features

- Glass Passivated Die Construction
- Diffused Junction
- Low Forward Voltage Drop, High Current Capability
- Surge Overload Rating to 50A Peak
- Designed for Surface Mount Application
- UL Listed Under Recognized Component Index, File Number E94661
- Lead Free Finish, RoHS Compliant (Note 3)

Mechanical Data

- Case: DF-S
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish - Matte Tin. Solderable per MIL-STD-202, Method 208
- Polarity: As marked on Case
- Marking: Type Number, See Page 3
- Weight: 0.38 grams (approximate)



DF-S		
Dim	Min	Max
A	7.40	7.90
B	6.20	6.50
C	0.22	0.30
D	0.076	0.33
E	—	10.40
G	1.02	1.53
H	8.13	8.51
J	2.40	2.60
K	5.00	5.20
L	1.00	1.20

All Dimensions in mm

Maximum Ratings and Electrical Characteristics

@ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, 60Hz, resistive or inductive load.

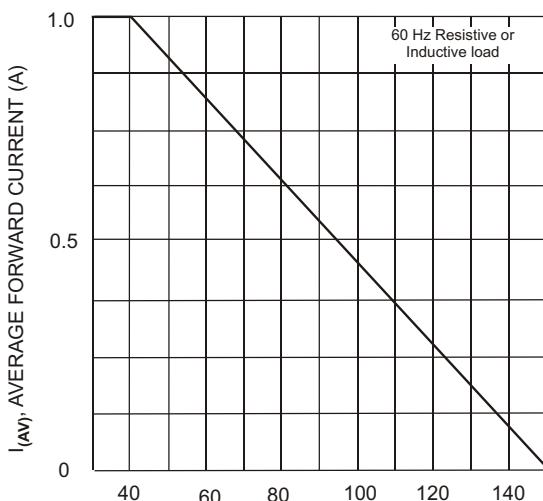
For capacitive load, derate current by 20%.

Characteristic	Symbol	DF 005S	DF 01S	DF 02S	DF 04S	DF 06S	DF 08S	DF 10S	Unit
Peak Repetitive Reverse Voltage	V_{RMM}								
Working Peak Reverse Voltage	V_{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V_R								
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Average Forward Rectified Current @ $T_A = 40^\circ\text{C}$	I_O				1.0				A
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}				50				A
Forward Voltage (per element) @ $I_F = 1.0\text{A}$	V_{FM}				1.1				V
Peak Reverse Current at Rated @ $T_A = 25^\circ\text{C}$	I_{RM}				10				μA
DC Blocking Voltage (per element) @ $T_A = 125^\circ\text{C}$					500				
I^2t Rating for Fusing ($t < 8.3\text{ms}$)	I^2t				10.4				A^2s
Typical Total Capacitance (per element) (Note 1)	C_T				25				pF
Typical Thermal Resistance, Junction to Ambient (Note 2)	$R_{\theta JA}$				40				$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{STG}				-65 to +150				$^\circ\text{C}$

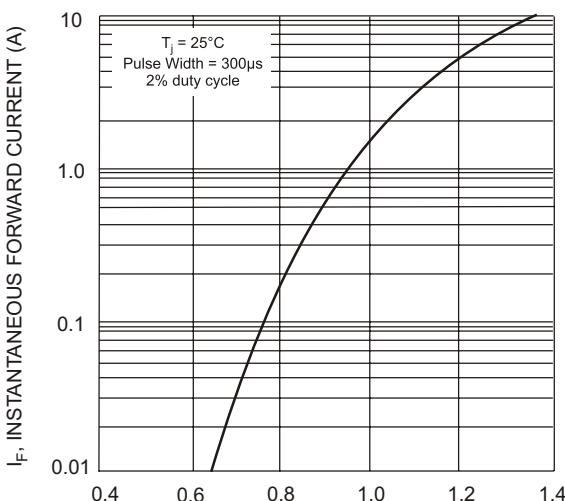
Notes: 1. Measured at 1.0 MHz and Applied Reverse Voltage of 4.0V DC.

2. Thermal resistance, junction to ambient, measured on PC board with 5.0mm^2 (0.03mm thick) land areas.

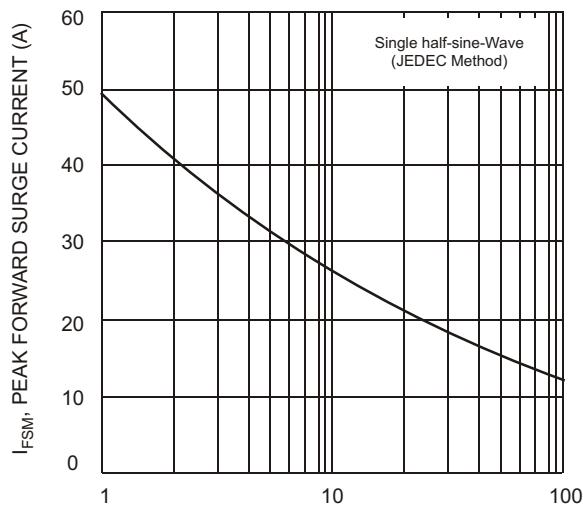
3. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.



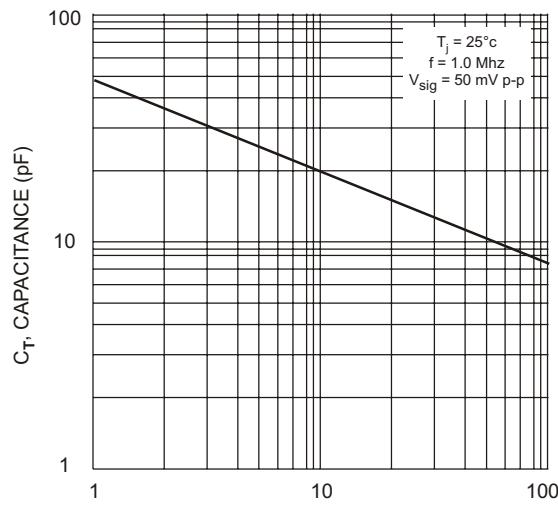
T_A , AMBIENT TEMPERATURE (°C)
Fig. 1 Output Current Derating Curve



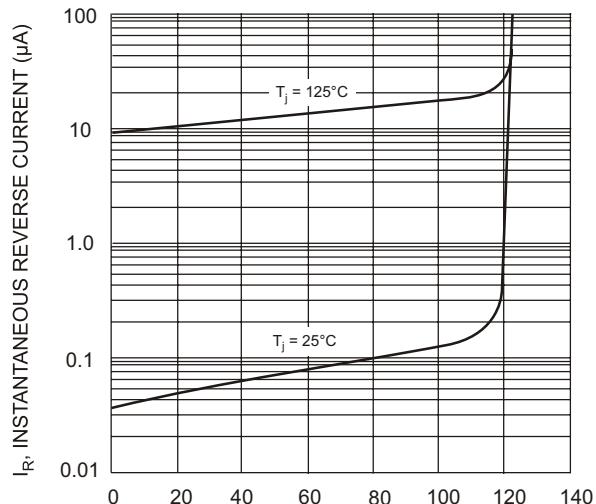
V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typ Forward Characteristics (per element)



NUMBER OF CYCLES AT 60 Hz
Fig. 3 Max Non-Repetitive Peak Forward Surge Current



V_R , REVERSE VOLTAGE (V)
Fig. 4 Typ Junction Capacitance (per element)



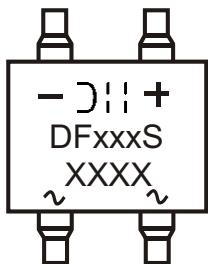
PERCENT OF RATED PEAK REVERSE VOLTAGE (%)
Fig. 5 Typ Reverse Characteristics (per element)

Ordering Information (Notes 4 & 5)

Device*	Packaging	Shipping
DFxS DFxS-T	DF-S DF-S	50 Per Tube 1500/Tape & Reel, 13-inch

* x = Device type, e.g. DF005S or DF10S, etc.

Notes: 4. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

DF = Manufacturers' code marking
DFxxxS = Product type marking code, ex: DF10S
YWW = Date code marking
Y = Last digit of year ex: 2 for 2002
WW = Week code 01 to 52